Title (en)

METHODS AND APPARATUS FOR MONITORING DEPOSITION QUALITY DURING CONFORMABLE CONTACT MASK PLATING OPERATIONS

Title (de)

VERFAHREN UND VORRICHTUNG ZUR ÜBERWACHUNG DER BESCHICHTUNGSQUALITÄT WÄHREND DES BESCHICHTUNGSVORGANGES IM KONFORMKONTAKTMASKENVERFAHREN

Title (fr)

PROCEDES ET APPAREIL DE SURVEILLANCE DE LA QUALITE DE DEPOT AU COURS D'OPERATIONS DE GALVANOPLASTIE EFFECTUEES A L'AIDE D'UN MASQUE DE CONTACT ADAPTABLE

Publication

EP 1506329 A1 20050216 (EN)

Application

EP 03726805 A 20030507

Priority

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Abstract (en)

[origin: WO03095715A1] Electrochemical fabrication (e.g. EFAB) processes and apparatus are disclosed that provide monitoring of at least one electrical parameter (e.g. voltage) during selective deposition where the monitored parameter is used to help determine the quality of the deposition that was made. If the monitored parameter indicates that a problem occurred with the deposition, various remedial operations may be undertaken to allow successful formation of the structure to be completed.

IPC 1-7

C25D 21/12; C25D 5/02; C25D 5/12; C25D 1/00

IPC 8 full level

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CPC (source: EP KR US)

B33Y 10/00 (2014.12 - EP KR US); **C25D 1/003** (2013.01 - EP KR US); **H01L 21/2885** (2013.01 - EP KR US); **H01L 21/76879** (2013.01 - EP KR US); H01L 21/4857 (2013.01 - EP KR US); H05K 3/241 (2013.01 - EP KR US); H05K 3/243 (2013.01 - EP KR US)

Citation (search report)

See references of WO 03095715A1

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